

FEATURES

$R_{DS(ON)} < 1.75\Omega @ V_{GS} = 10V$
Fast Switching Capability
Avalanche Energy Specified
Improved dv/dt Capability, High Ruggedness

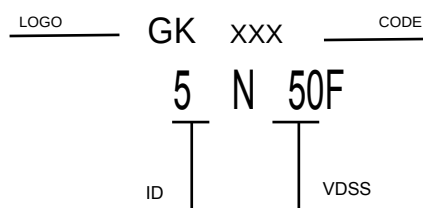
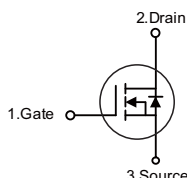


ITO-220AB



APPLICATION

High frequency switching mode power supply
Electronic ballast
LED power supply



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	500	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	Continuous	I_D	5	A
	Pulsed (Note 2)	I_{DM}	20	A
Avalanche Current (Note 2)		I_{AR}	5	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	300	mJ
	Repetitive (Note 2)	E_{AR}	7.3	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation		P_D	125	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~+150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3. $L = 21.5\text{mH}$, $I_{AS} = 5\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 5\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

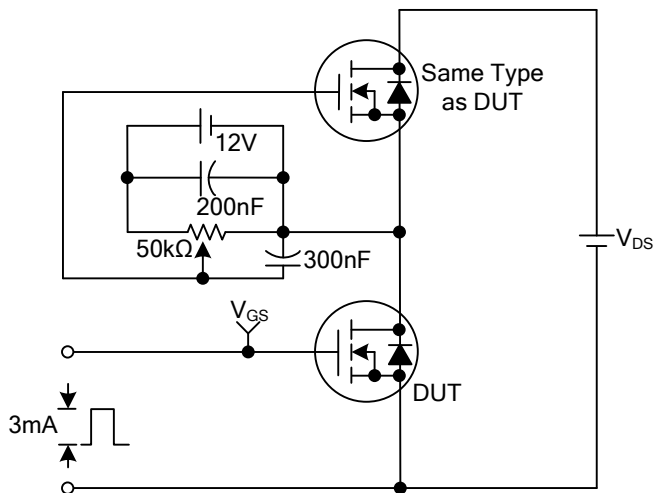
ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	I _D =250μA, V _{GS} =0V	500			V
Breakdown Voltage Temperature Coefficient		ΔBV _{DSS} /ΔT _J	Reference to 25°C, I _D =250μA		0.5		V/°C
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			1	μA
			V _{DS} =400V, T _C =125°C			10	
Gate- Source Leakage Current	Forward	I _{GSS}	V _{GS} =30V, V _{DS} =0V			100	nA
	Reverse		V _{GS} =-30V, V _{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =2.5A		1.45	1.75	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C _{ISS}	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		480	625	pF
Output Capacitance		C _{OSS}			80	105	pF
Reverse Transfer Capacitance		C _{RSS}			15	20	pF
SWITCHING PARAMETERS							
Total Gate Charge		Q _G	V _{GS} =10V, V _{DS} =400V, I _D =5A (Note 1, 2)		18	24	nC
Gate to Source Charge		Q _{GS}			2.2		nC
Gate to Drain Charge		Q _{GD}			9.7		nC
Turn-ON Delay Time		t _{D(ON)}	V _{DD} =250V, I _D =5A, R _G =25Ω (Note 1, 2)		12	35	ns
Rise Time		t _R			46	100	ns
Turn-OFF Delay Time		t _{D(OFF)}			50	110	ns
Fall-Time		t _F			48	105	ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Continuous Drain-Source Diode Forward Current		I _S				5	A
Maximum Pulsed Drain-Source Diode Forward Current		I _{SM}				20	A
Drain-Source Diode Forward Voltage		V _{SD}	I _S =5A, V _{GS} =0V			1.4	V
Reverse Recovery Time		t _{rr}	I _S =5A, V _{GS} =0V,		83		ns
Reverse Recovery Charge		Q _{RR}	dI _F /dt=100A/μs (Note 1)		0.25		uC

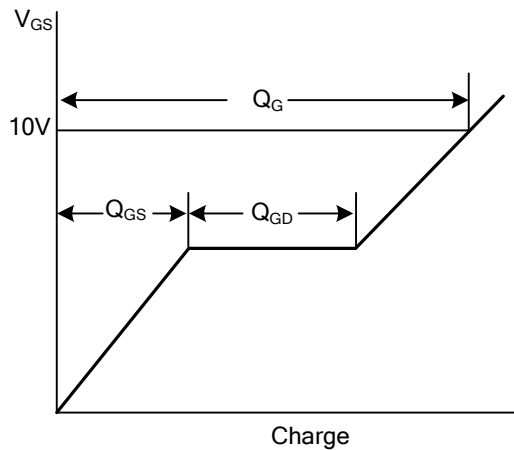
Note: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

2. Essentially independent of operating temperature

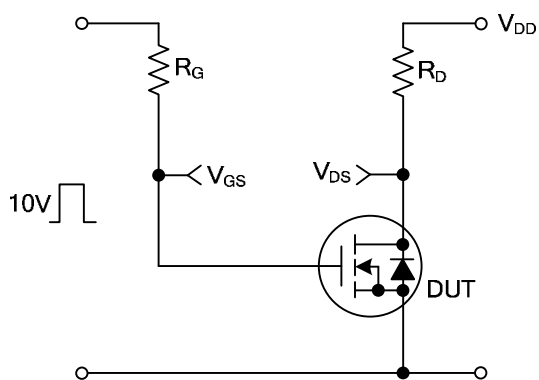
Test Circuit and Waveforms



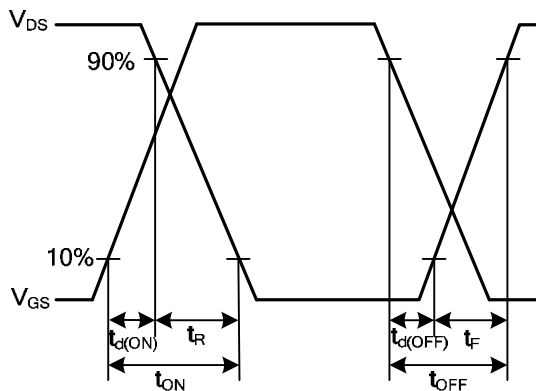
Gate Charge Test Circuit



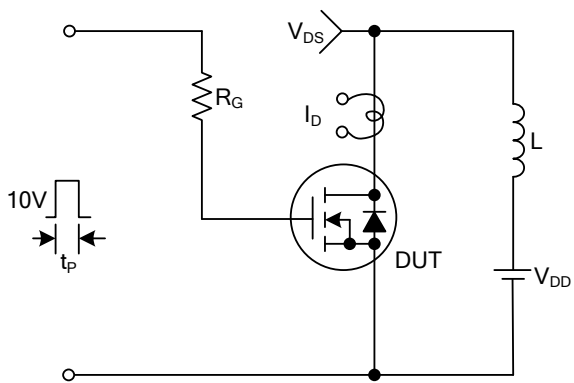
Gate Charge Waveforms



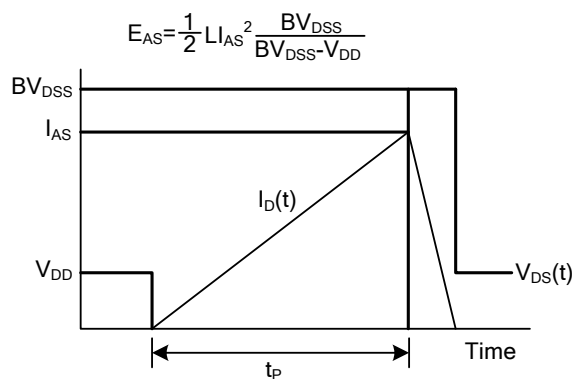
Resistive Switching Test Circuit



Resistive Switching Waveforms



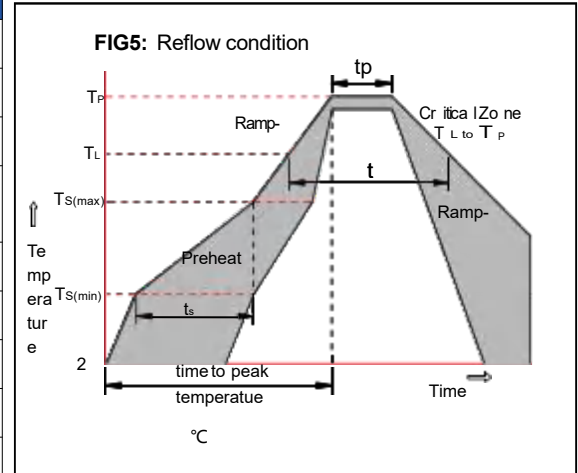
Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

